

Flex-RV: World's First Non-silicon RISC-V Microprocessor

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Company & FlexIC Technology

World leader in low-cost "physically" flexible integrated circuits or FlexICs

Flexible Wafer



FlexIC Facts

Transistor: Metal-oxide thin-film transistor (TFT) **Semiconductor:** IGZO (Indium Gallium Zinc Oxide)

Devices: n-type IGZO TFT, dedicated resistor & MiM capacitor

Substrate: Polyimide with total thickness <30 µm **Process geometry:** <=0.8 µm channel length

Logic: Resistive n-type Fab: Low-cost lithography Wafer Size: 200/300mm Supply Voltage: <=3V Routable metal layers: 4 Memory: ROM & LPROM

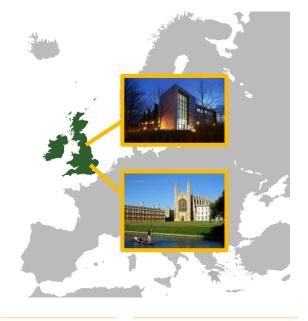
Under development CMOS, EPROM, SRAM/SRAM compiler)

FlexIC





FlexLogic Fab - 1000m² footprint



2010 Founded

~370

Employees

Cambridge Durham

UK headquarters UK manufacturing

>\$400Mn

Investment to date



Flex-RV: Bendable RISC-V Microprocessor

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Bendable non-silicon RISC-V microprocessor

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Collaboration







Milestones

- First non-silicon RISC-V microprocessor
- Integrated ML capability
- Assembled onto a FlexPCB
- Demonstration of functionality while physically flexed

Motivation: Extreme Edge Applications

Fast Moving Consumer Goods (FMCG)





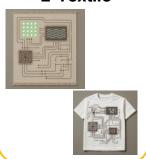
Healthcare





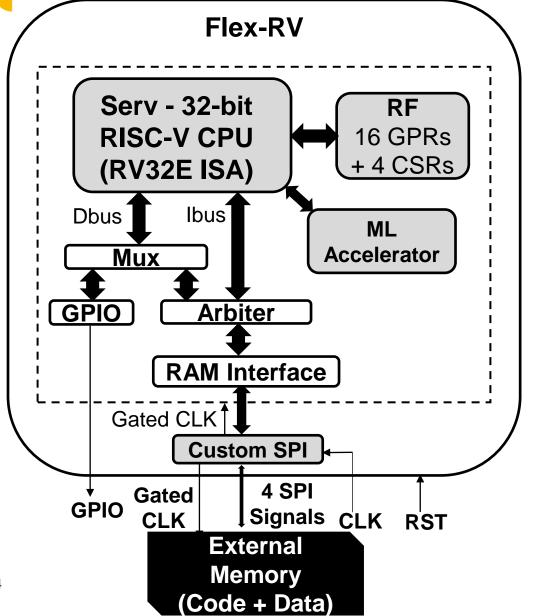


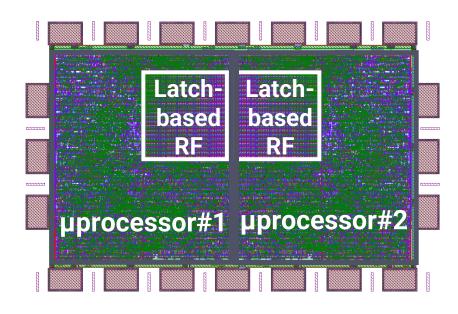
E-Textile





Flex-RV Design & Implementation

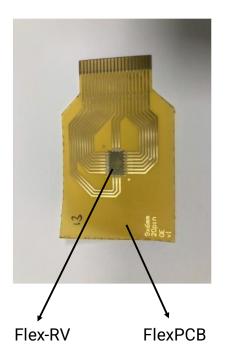


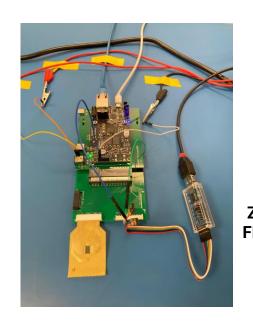


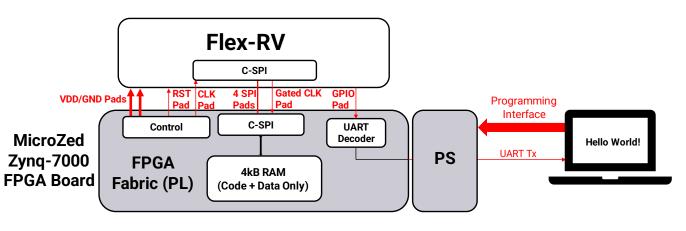
Technology	0.6 µm resistive n-type FlexIC
Area	17.49 mm² per Flex-RV microprocessor
Gatecount	12,596 NAND2-equivalent per Flex-RV microprocessor
Implementation Clock Frequency	61 kHz
Power	5.79 mW @3V per Flex-RV microprocessor

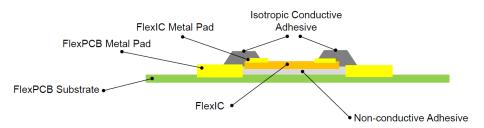


Assembly of Flex-RV onto a FlexPCB and Tests

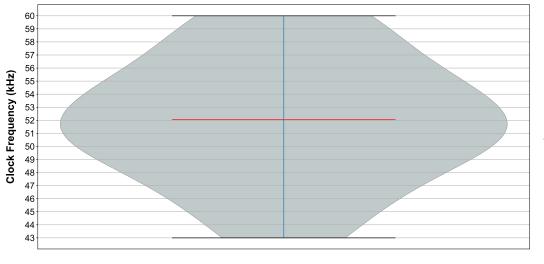








Over-Edge Printing



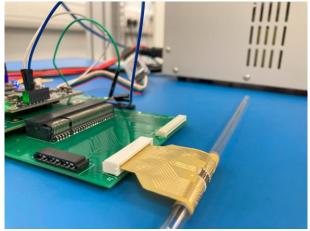
Average: 52kHz

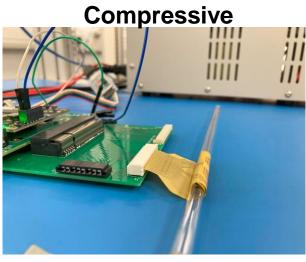
Max: 60kHz

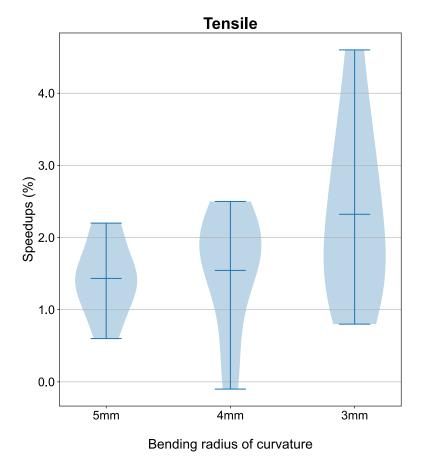


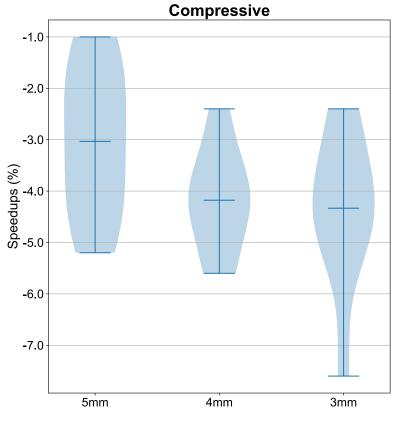
Bending Tests

Tensile









Bending radius of curvature









Flex-RV is the first programmable and physically flexible general-purpose RISC-V microprocessor, featuring machine learning capabilities, and demonstrated to bend below a 5mm radius of curvature whilst still executing programs, all for less than a dollar.



First **non-silicon RISC-V processor** and can run arbitrary compiled programs written in high-level languages (e.g., C)

Integrated programmable ML accelerator with custom RISC-V instructions support to accelerate ML applications

Demonstration of functionality and dynamic bendability of the assembled system (i.e., Flex-RV on Flex-PCB)

Questions?

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